



PCN#20150520001

**Qualification of Clark as new Assembly Site and conversion to lead-free assembly
process of TPS6208(X)RLT Family of Devices
Change Notification / Sample Request**

Date: 5/21/2015
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_wv_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150520001

Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS62085RLTR	null
TPS62085RLTT	null
TPS62086RLTT	null
TPS62087RLTT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150520001			PCN Date:	5/21/2015																		
Title:	Qualification of Clark as new Assembly Site and conversion to lead-free assembly process of TPS6208(X)RLT family of devices																						
Customer Contact:	PCN Manager	Dept:	Quality Services																				
Proposed 1st Ship Date:		08/21/2015	Estimated Sample Availability:		Provided upon Request																		
Change Type:																							
<input checked="" type="checkbox"/> Assembly Site		<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials																		
<input type="checkbox"/> Design		<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																		
<input checked="" type="checkbox"/> Test Site		<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																		
<input type="checkbox"/> Wafer Bump Site		<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																		
<input type="checkbox"/> Wafer Fab Site		<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																		
		<input type="checkbox"/>	Part number change																				
PCN Details																							
Description of Change:																							
<p>Texas Instruments is pleased to announce the qualification of TI Clark for the devices listed below. Devices assembled in TI Clark facility will be Pb-Free/RoHS Compliant. Devices assembled in UTAC will remain RoHS Exempt. Site differences are noted below.</p>																							
Pillar Solder Composition		UTAC		TI Clark																			
SnPb				SnAg																			
ECAT		E4		G4																			
<p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>																							
Reason for Change:																							
Continuity of Supply																							
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																							
None																							
Changes to product identification resulting from this PCN:																							
<table border="1"> <tr> <td colspan="2">Assembly Site</td> <td colspan="2"></td> <td colspan="2"></td> </tr> <tr> <td>UTAC</td> <td></td> <td colspan="2">Assembly Site Origin (22L)</td> <td colspan="2">ASO: NSE</td> </tr> <tr> <td>TI Clark</td> <td></td> <td colspan="2">Assembly Site Origin (22L)</td> <td colspan="2">ASO: QAB</td> </tr> </table>						Assembly Site						UTAC		Assembly Site Origin (22L)		ASO: NSE		TI Clark		Assembly Site Origin (22L)		ASO: QAB	
Assembly Site																							
UTAC		Assembly Site Origin (22L)		ASO: NSE																			
TI Clark		Assembly Site Origin (22L)		ASO: QAB																			
Sample product shipping label (not actual product label)																							
 TEXAS INSTRUMENTS MADE IN: Malaysia 20: 2DC: 20: MSL 2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04			(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO:MLA (23L) ACO:MYS																				
Topside Device marking: Assembly site code for NSE= J Assembly site code for QAB = I																							

Product Affected				
TPS62085RLTR	TPS62086RLTR	TPS62087RLTR	TPS62087RLTT	
TPS62085RLTT	TPS62086RLTT			



TI Information
Selective Disclosure

Qualification Report

TPS62085RLT
Approved
05/06/2015

Product Attributes

Attributes	Qual Device: TPS62085RLT	QBS Product: TPS62085RLT	QBS Process: TPS62110RSA
Assembly Site	CLARK AT	UTAC	CAR
Package Family	SON	SON	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Site	MIHO8	MIHO8	MIHO8
Wafer Fab Process	LBC7	LBC7	LBC7

- QBS: Qual By Similarity

- Qual Device TPS62085RLT is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS62085RLT	QBS Product: TPS62085RLT	QBS Process: TPS62110RSA
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-	3/231/0
AC	Autoclave 121C	96 Hours	3/231/0	-	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	3/231/0	-	-
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	1/77/0	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	1/77/0	-
HTOL	Life Test, 140C	480 Hours	-	-	3/231/0
ELFR	Early Life Failure Rate, 140C	48 Hours	-	-	3/1881/0
SD	Solderability	8 Hours Steam Age	3/66/0	-	-
PD	Physical Dimensions	--	3/15/0	-	-

HBM	ESD HBM	2500 V	-	1/3/0	-
CDM	ESD - CDM	1500 V	3/9/0	-	-
LU	Latch-up	(per JESD78)	-	1/6/0	3/15/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com